



FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTE
*	12.0	PLATED	426	MAX DIA
*	12.01	PLATED	43	MAX DIA / FIL
*	16.0	PLATED	80	MAX DIA
*	20.0	PLATED	659	MAX DIA
*	20.01	PLATED	16	MAX DIA / FIL
*	30.0	PLATED	3	
o	35.0	PLATED	11	
o	40.0	PLATED	40	
o	45.0	PLATED	68	
r	60.0	PLATED	25	
E	75.0	PLATED	3	
D	90.0	PLATED	2	
A	140.0	NON-PLATED	4	

1. REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
2. ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST0011S, (LATEST REVISION.)
3. MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
4. HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
5. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
6. HOLE DIAMETERS APPLY AFTER PLATING.
7. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
8. MINIMUM DESIGN LINE WIDTH IS .006 INCH.
9. MINIMUM DESIGN SPACING IS .004 INCH.
10. NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.
11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNUAL RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO LEAD DROP PADS TO MAINTAIN ANNUAL RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
12. THEIVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
13. A. CHIVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURED COPPER THICKNESS AS A REQUIREMENT FOR NEXT D.
14. B. THERE SHALL BE NO THEIVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
15. MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED:
  - A. UL CODE-FLAMMABILITY RATING D.
  - B. MFR LOGO
  - C. DATE CODE (STAMP).
  - E. SUCCESSFUL ELECTRICAL TEST
  - C. LOT NUMBER
16. REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED.
17. TOP SURF FILLED WITH NON-CONDUCTIVE EPOXY AND PLATED OVER. COPLANAR ON THE TOP SIDE PRIOR TO FINAL PLATING.
18. ALL GOLD LAYERS (L2 AND L4), BOTTOM, AND THE TOP LAYER WILL NEED TO HAVE TWO (2) INCHES OF COPPER THICKNESS AS A REQUIREMENT FOR NEXT D RECOMMENDATIONS/SUGGESTIONS WILL NEED CUSTOMER APPROVAL.
19. PLEASE TAKE NOTE THAT THERE ARE TWO VERSIONS OF SOLDERMASK TOP FOR THIS BOARD. IT IS THE CUSTOMER'S DISCRETION TO CHOOSE WHICH FOR THE FABRICATION. CUSTOMER WILL INFORM THE FABHOUSE BEFOREHAND. THE TWO VERSIONS SOLDERMASKS ARE NAMED AS FOLLOWS: SOLDERMASK PRIMA SECONDARY V2.)

[illegible]